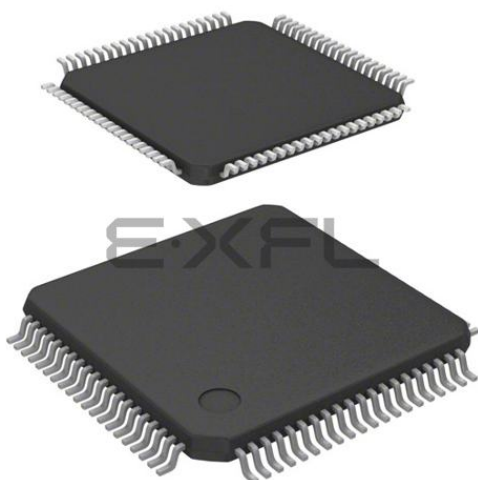




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Details

Product Status	Obsolete
Core Processor	H8/300L
Core Size	8-Bit
Speed	8MHz
Connectivity	SCI
Peripherals	LCD, PWM, WDT
Number of I/O	51
Program Memory Size	32KB (32K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 75°C (TA)
Mounting Type	Surface Mount
Package / Case	80-TQFP
Supplier Device Package	80-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/hd64738024wv

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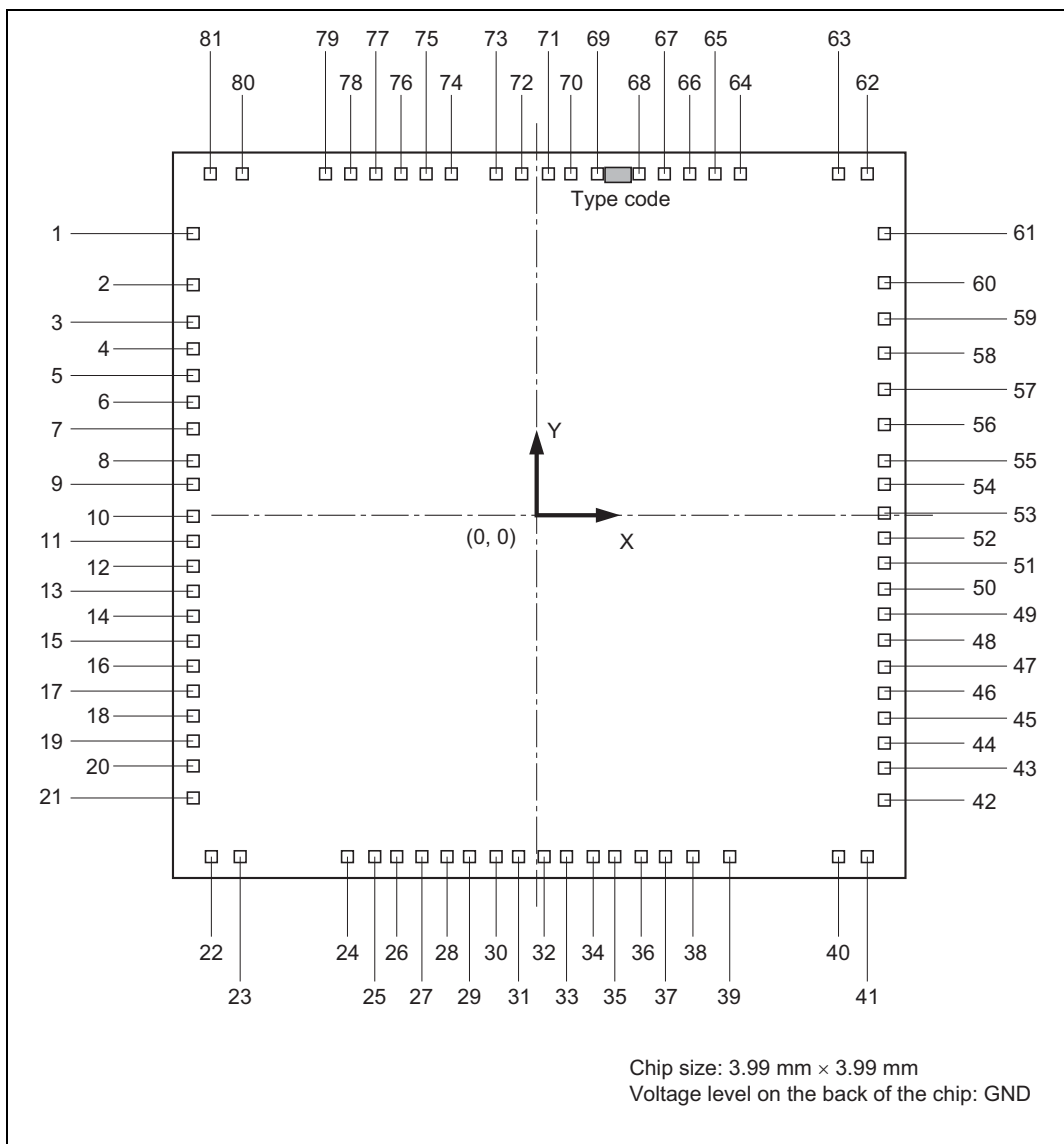


Figure 1.5 Bonding Pad Location Diagram of HCD64338024, HCD64338023, HCD64338022, HCD64338021, and HCD64338020 (Top View)

2.2 Register Descriptions

2.2.1 General Registers

All the general registers can be used as both data registers and address registers.

When used as data registers, they can be accessed as 16-bit registers (R0 to R7), or the high bytes (R0H to R7H) and low bytes (R0L to R7L) can be accessed separately as 8-bit registers.

When used as address registers, the general registers are accessed as 16-bit registers (R0 to R7).

R7 also functions as the stack pointer (SP), used implicitly by hardware in exception processing and subroutine calls. When it functions as the stack pointer, as indicated in figure 2.2, SP (R7) points to the top of the stack.

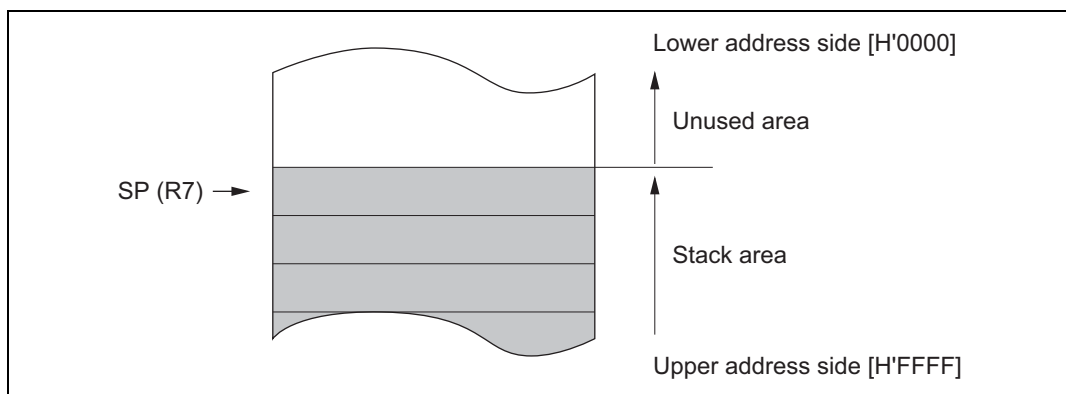


Figure 2.2 Stack Pointer

2.2.2 Control Registers

The CPU control registers include a 16-bit program counter (PC) and an 8-bit condition code register (CCR).

Program Counter (PC)

This 16-bit register indicates the address of the next instruction the CPU will execute. All instructions are fetched 16 bits (1 word) at a time, so the least significant bit of the PC is ignored (always regarded as 0).

2.5.1 Data Transfer Instructions

Table 2.4 describes the data transfer instructions. Figure 2.5 shows their object code formats.

Table 2.4 Data Transfer Instructions

Instruction	Size*	Function
MOV	B/W	(EAs) → Rd, Rs → (EAd) Moves data between two general registers or between a general register and memory, or moves immediate data to a general register. The Rn, @Rn, @(d:16, Rn), @aa:16, #xx:16, @-Rn, and @Rn+ addressing modes are available for word data. The @aa:8 addressing mode is available for byte data only. The @-R7 and @R7+ modes require word operands. Do not specify byte size for these two modes.
POP	W	@SP+ → Rn Pops a 16-bit general register from the stack. Equivalent to MOV.W @SP+, Rn.
PUSH	W	Rn → @-SP Pushes a 16-bit general register onto the stack. Equivalent to MOV.W Rn, @-SP.

Note: * Size: Operand size
 B: Byte
 W: Word

Certain precautions are required in data access. See section 2.9.1, Notes on Data Access, for details.

Figure 2.7 lists the format of the bit manipulation instructions.

When system power is turned on or off, the $\overline{\text{RES}}$ pin should be held low.

Figure 3.1 shows the reset sequence starting from $\overline{\text{RES}}$ input.

See section 14.3.1, Power-On Reset Circuit, for information on the reset sequence for the H8/38124 Group, which is equipped with an on-chip power-on reset circuit.

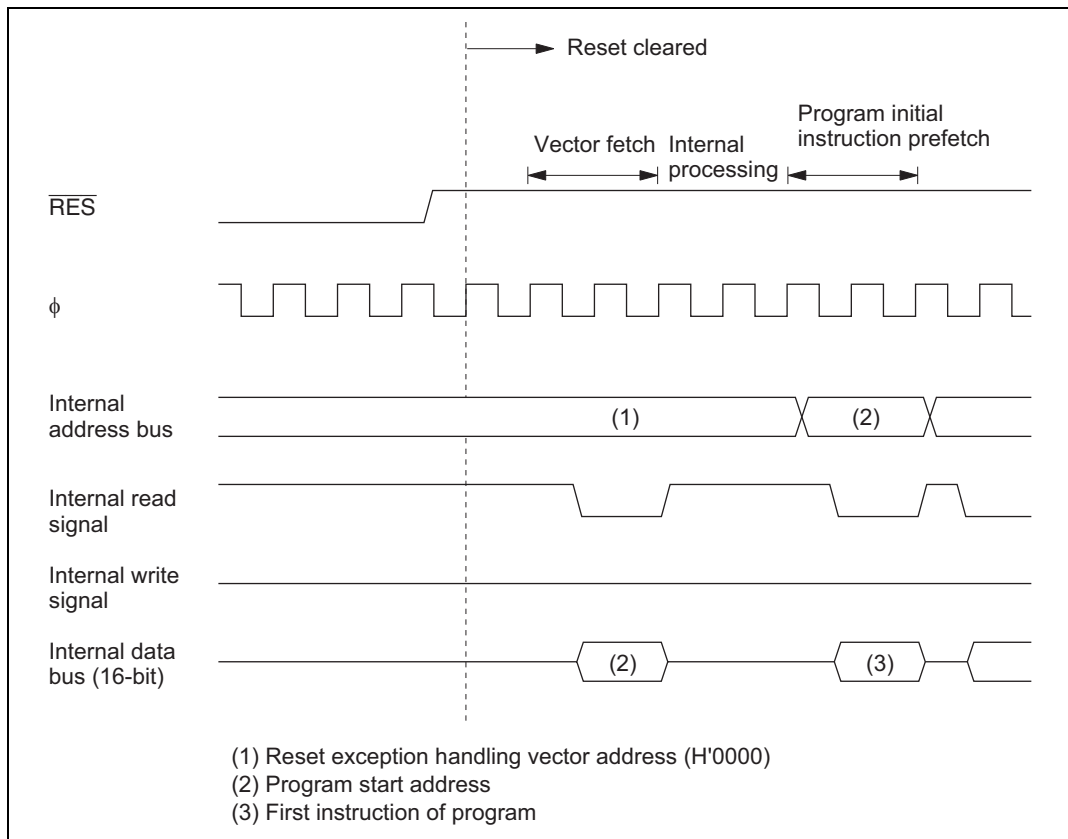


Figure 3.1 Reset Sequence

3.2.3 Interrupt Immediately after Reset

After a reset, if an interrupt were to be accepted before the stack pointer (SP: R7) was initialized, PC and CCR would not be pushed onto the stack correctly, resulting in program runaway. To prevent this, immediately after reset exception handling all interrupts are masked. For this reason, the initial program instruction is always executed immediately after a reset. This instruction should initialize the stack pointer (e.g. MOV.W #xx: 16, SP).

amplitude of the oscillation waveform increases and the oscillation frequency stabilizes—that is, the oscillation stabilization time—is required.

The oscillation stabilization time in the case of these state transitions is the same as the oscillation stabilization time at power-on (the time from the point at which the power supply voltage reaches the prescribed level until the oscillation stabilizes), specified by "oscillation stabilization time t_{rc} " in the AC characteristics.

Meanwhile, once the system clock has halted, a wait time of at least 8 states is necessary in order for the CPU and peripheral functions to operate normally.

Thus, the time required from interrupt generation until operation of the CPU and peripheral functions is the sum of the above described oscillation stabilization time and wait time. This total time is called the oscillation stabilization wait time, and is expressed by equation (1) below.

$$\begin{aligned}\text{Oscillation stabilization wait time} &= \text{oscillation stabilization time} + \text{wait time} \\ &= t_{rc} + (8 \text{ to } 16,384 \text{ states})^{*1} \dots\dots\dots (1) \\ &\quad (\text{up to } 131,072 \text{ states})^{*2}\end{aligned}$$

- Notes: 1. H8/38024 Group
2. H8/38124 Group

Therefore, when a transition is made from standby mode, watch mode, or subactive mode, to active (high-speed/medium-speed) mode, with an oscillator element connected to the system clock oscillator, careful evaluation must be carried out on the installation circuit before deciding on the oscillation stabilization wait time. In particular, since the oscillation stabilization time is affected by installation circuit constants, stray capacitance, and so forth, suitable constants should be determined in consultation with the oscillator element manufacturer.

4.5.2 Notes on Use of Crystal Oscillator Element (Excluding Ceramic Oscillator Element)

When a microcomputer operates, the internal power supply potential fluctuates slightly in synchronization with the system clock. Depending on the individual crystal oscillator element characteristics, the oscillation waveform amplitude may not be sufficiently large immediately after the oscillation stabilization wait time, making the oscillation waveform susceptible to influence by fluctuations in the power supply potential. In this state, the oscillation waveform may be disrupted, leading to an unstable system clock and erroneous operation of the microcomputer.

If erroneous operation occurs, change the setting of standby timer select bits 2 to 0 (STS2 to STS0) (bits 6 to 4 in system control register 1 (SYSCR1)) to give a longer wait time.

Bits 6 to 4—Standby Timer Select 2 to 0 (STS2 to STS0)

These bits designate the time the CPU and peripheral modules wait for stable clock operation after exiting from standby mode or watch mode to active mode due to an interrupt. The designation should be made according to the operating frequency so that the waiting time is at least equal to the oscillation stabilization time. Note that stabilization times for the H8/38024, H8/38024S, and H8/38024R Group and for the H8/38124 Group are different.

- H8/38024, H8/38024S, H8/38024R Group**

Bit 6 STS2	Bit 5 STS1	Bit 4 STS0	Description
0	0	0	Wait time = 8,192 states (initial value)
0	0	1	Wait time = 16,384 states
0	1	0	Wait time = 1,024 states
0	1	1	Wait time = 2,048 states
1	0	0	Wait time = 4,096 states
1	0	1	Wait time = 2 states (External clock input mode)
1	1	0	Wait time = 8 states
1	1	1	Wait time = 16 states

- H8/38124 Group**

Bit 6 STS2	Bit 5 STS1	Bit 4 STS0	Description
0	0	0	Wait time = 8,192 states (initial value)
0	0	1	Wait time = 16,384 states
0	1	0	Wait time = 32,768 states
0	1	1	Wait time = 65,536 states
1	0	0	Wait time = 131,072 states
1	0	1	Wait time = 2 states (External clock input mode)
1	1	0	Wait time = 8 states
1	1	1	Wait time = 16 states

Note: If an external clock is being input, set standby timer select to external clock mode before mode transition. Also, do not set standby timer select to external clock mode if no external clock is used. 8,192 states (STS2 = STS1 = STS0 = 0) is recommended if the on-chip oscillator is used on the H8/38124 Group.

3. When the boot program is initiated, the chip measures the low-level period of asynchronous SCI communication data (H'00) transmitted continuously from the host. The chip then calculates the bit rate of transmission from the host, and adjusts the SCI3 bit rate to match that of the host. The reset should end with the RXD pin high. The RXD and TXD pins should be pulled up on the board if necessary. After the reset is complete, it takes approximately 100 states before the chip is ready to measure the low-level period.
4. After matching the bit rates, the chip transmits one H'00 byte to the host to indicate the completion of bit rate adjustment. The host should confirm that this adjustment end indication (H'00) has been received normally, and transmit one H'55 byte to the chip. If reception could not be performed normally, initiate boot mode again by a reset. Depending on the host's transfer bit rate and system clock frequency of this LSI, there will be a discrepancy between the bit rates of the host and the chip. To operate the SCI properly, set the host's transfer bit rate and system clock frequency of this LSI within the ranges listed in table 6.9.
5. In boot mode, a part of the on-chip RAM area is used by the boot program. The area H'F780 to H'FEFF is the area to which the programming control program is transferred from the host. The boot program area cannot be used until the execution state in boot mode switches to the programming control program.
6. Before branching to the programming control program, the chip terminates transfer operations by SCI3 (by clearing the RE and TE bits in SCR to 0), however the adjusted bit rate value remains set in BRR. Therefore, the programming control program can still use it for transfer of write data or verify data with the host. The TXD pin is high (PCR42 = 1, P42 = 1). The contents of the CPU general registers are undefined immediately after branching to the programming control program. These registers must be initialized at the beginning of the programming control program, as the stack pointer (SP), in particular, is used implicitly in subroutine calls, etc.
7. Boot mode can be cleared by a reset. End the reset after driving the reset pin low, waiting at least 20 states, and then setting the TEST pin and P95 pin. Boot mode is also cleared when a WDT overflow occurs.
8. Do not change the TEST pin and P95 pin input levels in boot mode.

Port Data Register 7 (PDR7)

Bit	7	6	5	4	3	2	1	0
	P7 ₇	P7 ₆	P7 ₅	P7 ₄	P7 ₃	P7 ₂	P7 ₁	P7 ₀
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

PDR7 is an 8-bit register that stores data for port 7 pins P7₇ to P7₀. If port 7 is read while PCR7 bits are set to 1, the values stored in PDR7 are read, regardless of the actual pin states. If port 7 is read while PCR7 bits are cleared to 0, the pin states are read.

Upon reset, PDR7 is initialized to H'00.

Port Control Register 7 (PCR7)

Bit	7	6	5	4	3	2	1	0
	PCR7 ₇	PCR7 ₆	PCR7 ₅	PCR7 ₄	PCR7 ₃	PCR7 ₂	PCR7 ₁	PCR7 ₀
Initial value	0	0	0	0	0	0	0	0
Read/Write	W	W	W	W	W	W	W	W

PCR7 is an 8-bit register for controlling whether each of the port 7 pins P7₇ to P7₀ functions as an input pin or output pin. Setting a PCR7 bit to 1 makes the corresponding pin an output pin, while clearing the bit to 0 makes the pin an input pin. PCR7 and PDR7 settings are valid when the corresponding pins are designated for general-purpose input/output by bits SGS3 to SGS0 in LPCR.

Upon reset, PCR7 is initialized to H'00.

PCR7 is a write-only register, which is always read as all 1s.

b. TCFL, OCRFL

In toggle output, TMOFL pin output is toggled when a compare match occurs. If a TCRF write by a MOV instruction and generation of the compare match signal occur simultaneously, TOLL data is output to the TMOFL pin as a result of the TCRF write.

If an OCRFL write and compare match signal generation occur simultaneously, the compare match signal is invalid. However, if the written data and the counter value match, a compare match signal will be generated at that point. As the compare match signal is output in synchronization with the TCFL clock, a compare match will not result in compare match signal generation if the clock is stopped.

If a TCFL write and overflow signal output occur simultaneously, the overflow signal is not output.

Clear Timer FH, Timer FL Interrupt Request Flags (IRRTFH, IRRTFL), Timer Overflow Flags H, L (OVFH, OVFL) and Compare Match Flags H, L (CMFH, CMFL)

When $\phi w/4$ is selected as the internal clock, “Interrupt factor generation signal” will be operated with ϕw and the signal will be outputted with ϕw width. And, “Overflow signal” and “Compare match signal” are controlled with 2 cycles of ϕw signals. Those signals are outputted with 2 cycles width of ϕw (figure 9.7)

In active (high-speed, medium-speed) mode, even if you cleared interrupt request flag during the term of validity of “Interrupt factor generation signal”, same interrupt request flag is set. (figure 9.7 (1)) And, you cannot be cleared timer overflow flag and compare match flag during the term of validity of “Overflow signal” and “Compare match signal”.

For interrupt request flag is set right after interrupt request is cleared, interrupt process to one time timer FH, timer FL interrupt might be repeated. (figure 9.7 (2)) Therefore, to definitely clear interrupt request flag in active (high-speed, medium-speed) mode, clear should be processed after the time that calculated with below (1) formula. And, to definitely clear timer overflow flag and compare match flag, clear should be processed after read timer control status register F (TCSRF) after the time that calculated with below (1) formula. For ST of (1) formula, please substitute the longest number of execution states in used instruction. (10 states of RTE instruction when MULXU, DIVXU instruction is not used, 14 states when MULXU, DIVXU instruction is used) In subactive mode, there are not limitation for interrupt request flag, timer overflow flag, and compare match flag clear.

10.1.2 Block Diagram

Figure 10.1 shows a block diagram of SCI3.

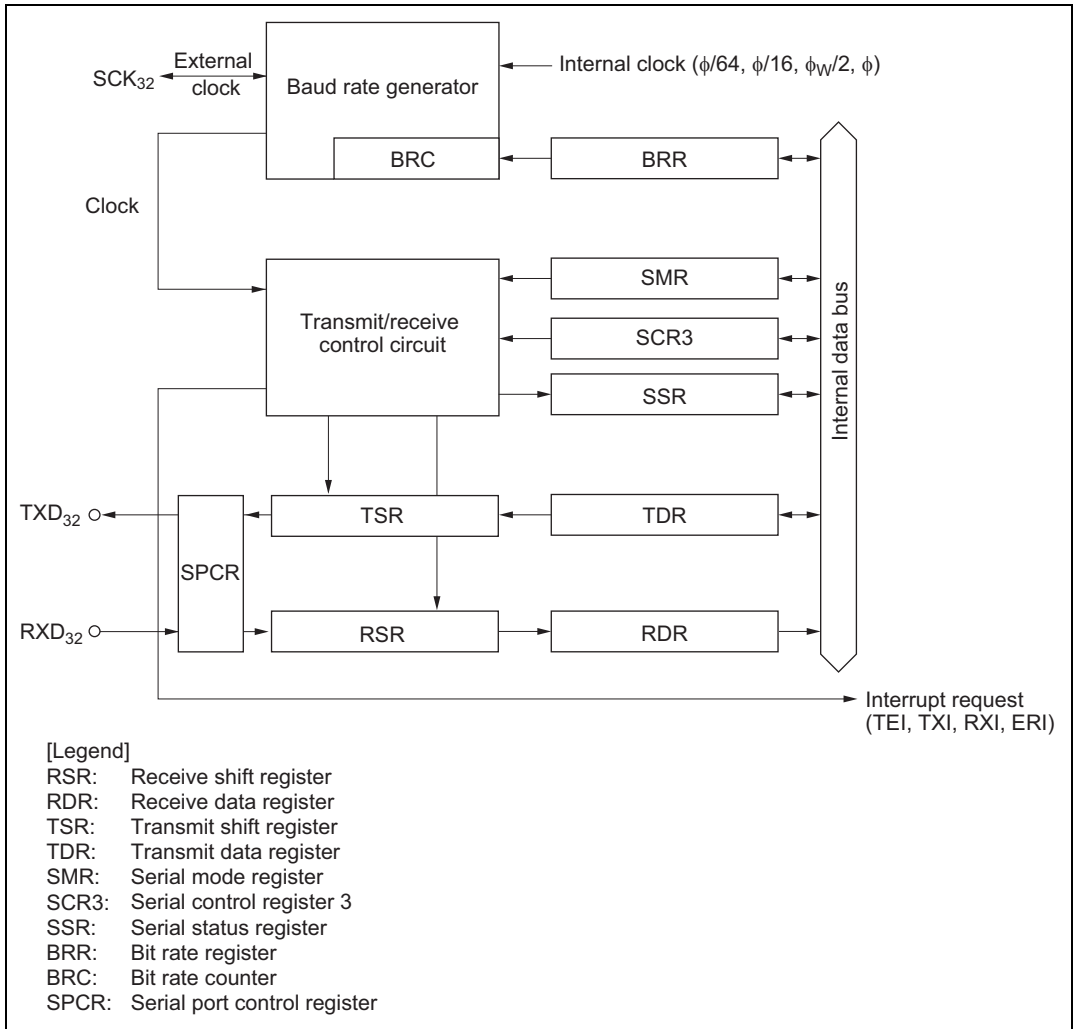


Figure 10.1 SCI3 Block Diagram

Clock

Either an internal clock generated by the baud rate generator or an external clock input at the SCK₃₂ pin can be selected as the SCI3 transmit/receive clock. The selection is made by means of bit COM in SMR and bits SCE1 and CKE0 in SCR3. See table 10.9 for details on clock source selection.

When an external clock is input at the SCK₃₂ pin, the clock frequency should be 16 times the bit rate.

When SCI3 operates on an internal clock, the clock can be output at the SCK₃₂ pin. In this case the frequency of the output clock is the same as the bit rate, and the phase is such that the clock rises at the center of each bit of transmit/receive data, as shown in figure 10.4.

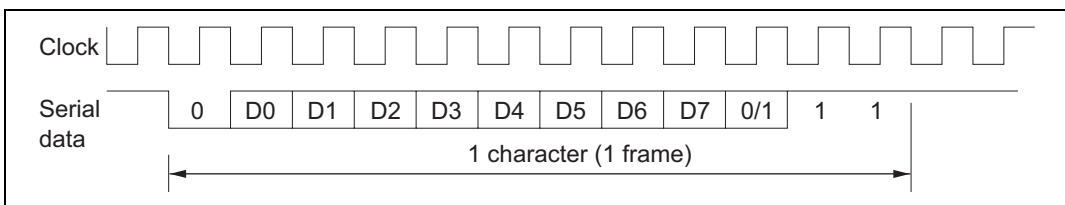


Figure 10.4 Phase Relationship between Output Clock and Transfer Data (Asynchronous Mode) (8-bit data, parity, 2 stop bits)

Data Transfer Operations

- SCI3 initialization

Before data is transferred on SCI3, bits TE and RE in SCR3 must first be cleared to 0, and then SCI3 must be initialized as follows.

Note: If the operation mode or data transfer format is changed, bits TE and RE must first be cleared to 0.

When bit TE is cleared to 0, bit TDRE is set to 1.

Note that the RDRF, PER, FER, and OER flags and the contents of RDR are retained when RE is cleared to 0.

When an external clock is used in asynchronous mode, the clock should not be stopped during operation, including initialization. When an external clock is used in synchronous mode, the clock should not be supplied during operation, including initialization.

10.5 Application Notes

The following points should be noted when using SCI3.

1. Relation between writes to TDR and bit TDRE

Bit TDRE in the serial status register (SSR) is a status flag that indicates that data for serial transmission has not been prepared in TDR. When data is written to TDR, bit TDRE is cleared to 0 automatically. When SCI3 transfers data from TDR to TSR, bit TDRE is set to 1.

Data can be written to TDR irrespective of the state of bit TDRE, but if new data is written to TDR while bit TDRE is cleared to 0, the data previously stored in TDR will be lost or it has not yet been transferred to TSR. Accordingly, to ensure that serial transmission is performed dependably, you should first check that bit TDRE is set to 1, then write the transmit data to TDR once only (not two or more times).

2. Operation when a number of receive errors occur simultaneously

If a number of receive errors are detected simultaneously, the status flags in SSR will be set to the states shown in table 10.14. If an overrun error is detected, data transfer from RSR to RDR will not be performed, and the receive data will be lost.

Table 10.14 SSR Status Flag States and Receive Data Transfer

SSR Status Flags				Receive Data Transfer	
RDRF*	OER	FER	PER	RSR → RDR	Receive Error Status
1	1	0	0	X	Overrun error
0	0	1	0	O	Framing error
0	0	0	1	O	Parity error
1	1	1	0	X	Overrun error + framing error
1	1	0	1	X	Overrun error + parity error
0	0	1	1	O	Framing error + parity error
1	1	1	1	X	Overrun error + framing error + parity error

O : Receive data is transferred from RSR to RDR.

X : Receive data is not transferred from RSR to RDR.

Note: * Bit RDRF retains its state prior to data reception. However, note that if RDR is read after an overrun error has occurred in a frame because reading of the receive data in the previous frame was delayed, RDRF will be cleared to 0.

Item	Symbol	Applicable Pins	Values			Unit	Test Condition	Notes
			Min	Typ	Max			
Input low voltage	V_{IL}	$\overline{RES}$, $\overline{WKP}_0$ to $\overline{WKP}_7$, $\overline{IRQ}_0$, $\overline{IRQ}_1$, $\overline{IRQ}_3$, $\overline{IRQ}_4$, $\overline{IRQAEC}$, P9 ^{*5} , AEVL, AEVH, TMIC, TMIF, $\overline{TMIG}$, $\overline{ADTRG}$, SCK ₃₂	-0.3	—	0.1 V_{CC}	V		
		RXD ₃₂ , UD	-0.3	—	0.2 V_{CC}	V		
		OSC ₁	-0.3	—	0.1 V_{CC}	V		
		X ₁	-0.3	—	0.1 V_{CC}	V		
		P1 ₃ , P1 ₄ , P1 ₆ , P1 ₇ , P3 ₀ to P3 ₇ , P4 ₀ to P4 ₃ , P5 ₀ to P5 ₇ , P6 ₀ to P6 ₇ , P7 ₀ to P7 ₇ , P8 ₀ to P8 ₇ , PA ₀ to PA ₃ , PB ₀ to PB ₇	-0.3	—	0.2 V_{CC}	V		
Output high voltage	V_{OH}	P1 ₃ , P1 ₄ ,	$V_{CC} - 1.0$	—	—	V	$-I_{OH} = 1.0 \text{ mA}$	
		P1 ₆ , P1 ₇ ,	$V_{CC} - 0.3$	—	—		$-I_{OH} = 0.1 \text{ mA}$	
		P3 ₀ to P3 ₇ ,						
		P4 ₀ to P4 ₂ ,						
		P5 ₀ to P5 ₇ ,						
		P6 ₀ to P6 ₇ ,						
		P7 ₀ to P7 ₇ , P8 ₀ to P8 ₇ , PA ₀ to PA ₃						

PCR1—Port Control Register 1**H'E4****I/O Ports**

Bit	7	6	5	4	3	2	1	0
	PCR1 ₇	PCR1 ₆ *	—	PCR1 ₄	PCR1 ₃	—	—	—
Initial value	0	0	—	0	0	—	—	—
Read/Write	W	W	W	W	W	W	W	W

SYSCR1—System Control Register 1

H'F0

System Control

Bit	7	6	5	4	3	2	1	0
	SSBY	STS2	STS1	STS0	LSON	—	MA1	MA0
Initial value	0	0	0	0	0	1	1	1
Read/Write	R/W	R/W	R/W	R/W	R/W	—	R/W	R/W

Active (medium-speed)
Mode Clock Select

0	0	$\phi_{osc}/16$
	1	$\phi_{osc}/32$
1	0	$\phi_{osc}/64$
	1	$\phi_{osc}/128$

Low Speed on Flag

0	The CPU operates on the system clock (ϕ)
1	The CPU operates on the subclock (ϕ_{SUB})

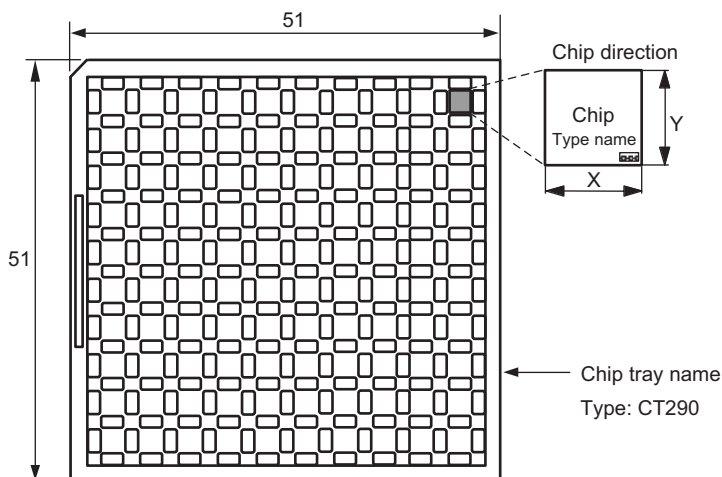
Standby Timer Select 2 to 0

0	0	0	Wait time = 8,192 states ^{*1}	Wait time = 8,192 states ^{*2}
		1	Wait time = 16,384 states ^{*1}	Wait time = 16,384 states ^{*2}
	1	0	Wait time = 1,024 states ^{*1}	Wait time = 32,768 states ^{*2}
		1	Wait time = 2,048 states ^{*1}	Wait time = 65,536 states ^{*2}
1	0	0	Wait time = 4,096 states ^{*1}	Wait time = 131,072 states ^{*2}
		1	Wait time = 2 states ^{*1}	Wait time = 2 states ^{*2}
	1	0	Wait time = 8 states ^{*1}	Wait time = 8 states ^{*2}
		1	Wait time = 16 states ^{*1}	Wait time = 16 states ^{*2}

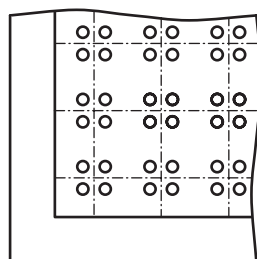
Software Standby

0	- When a SLEEP instruction is executed in active mode, a transition is made to sleep mode - When a SLEEP instruction is executed in subactive mode, a transition is made to subsleep mode
1	- When a SLEEP instruction is executed in active mode, a transition is made to standby mode or watch mode - When a SLEEP instruction is executed in subactive mode, a transition is made to watch mode

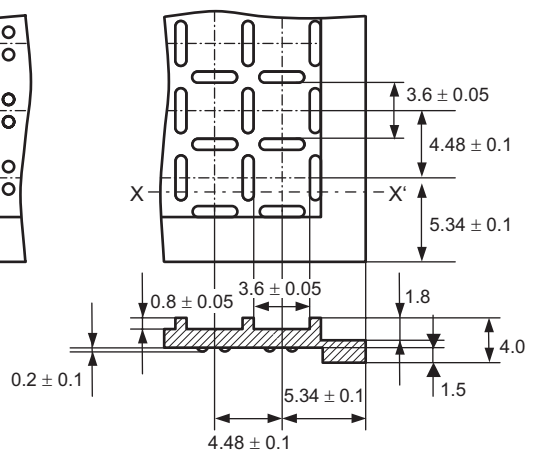
Notes: 1. Applies to products other than the H8/38124 Group.
 2. Applies to the H8/38124 Group.



Carved code:TCT036036-060T



Back of chip tray



X-X' Cross section

unit: mm

Figure I.3 Specifications of Chip Tray for the HCD64338024S, HCD64338023S, HCD64338022S, HCD64338021S, and HCD64338020S

Item	Page	Revision (See Manual for Details)
Appendix F Package Dimensions Figure F.4 TLP-85V Package Dimensions	642	Figure replaced
Appendix I Specifications of Chip Tray Figure I.3 Specifications of Chip Tray for the HCD64338024S, HCD64338023S, HCD64338022S, HCD64338021S, and HCD64338020S	648	Figure replaced